



Material Content Data Sheet



Sales Product Name		IPG20N06S4L-26A		Issued		31. July 2018		
MA#		MA002193004						
Package		PG-TDSON-8-10		Weight*		98.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.783	0.79	0.79	7948	7948
chip_2	inorganic material	silicon	7440-21-3	0.783	0.79	0.79	7948	7948
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		141	
	non noble metal	iron	7439-89-6	0.046	0.05		471	
	non noble metal	copper	7440-50-8	46.380	47.07	47.13	470567	471179
	non noble metal	aluminium	7429-90-5	0.789	0.80	0.80	8006	8006
wire	organic material	carbon black	1333-86-4	0.091	0.09		921	
	plastics	epoxy resin	-	6.444	6.54		65379	
encapsulation	inorganic material	silicondioxide	60676-86-0	38.845	39.41	46.04	394113	460413
	non noble metal	tin	7440-31-5	1.396	1.42	1.42	14168	14168
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6119	6134
solder	non noble metal	tin	7440-31-5	0.048	0.05		484	
	noble metal	silver	7440-22-4	0.060	0.06		605	
	non noble metal	lead	7439-92-1	2.278	2.31	2.42	23115	24204
	*deviation	< 10%		Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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